



US00D401249S

**United States Patent** [19]  
**Kawakita**

[11] **Patent Number: Des. 401,249**  
[45] **Date of Patent: \*\*Nov. 17, 1998**

[54] **ROLLER FOR A WIRE SAW FOR SEMICONDUCTORS**

5,715,807 2/1998 Toyama et al. .... 125/16.02

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[57] **CLAIM**

[\*\*] Term: **14 Years**

The ornamental design for a roller for a wire saw for semiconductors, as shown and described.

[21] Appl. No.: **75,089**

**DESCRIPTION**

[22] Filed: **Aug. 12, 1997**

FIG. 1 is a front elevational view of a roller for a wire saw for semiconductors, the rear elevational view being a mirror image of FIG. 1;

[51] **LOC (6) Cl.** ..... **15-09**

[52] **U.S. Cl.** ..... **D15/133; D15/138**

FIG. 2 is a top plan view thereof, the bottom plan view being identical with FIG. 2;

[58] **Field of Search** ..... D15/133, 138, D15/139; 83/651.1, 171; 125/16.02

FIG. 3 is a right side elevational view thereof, the left side elevational view being identical with FIG. 3;

FIG. 4 is a perspective view thereof; and,

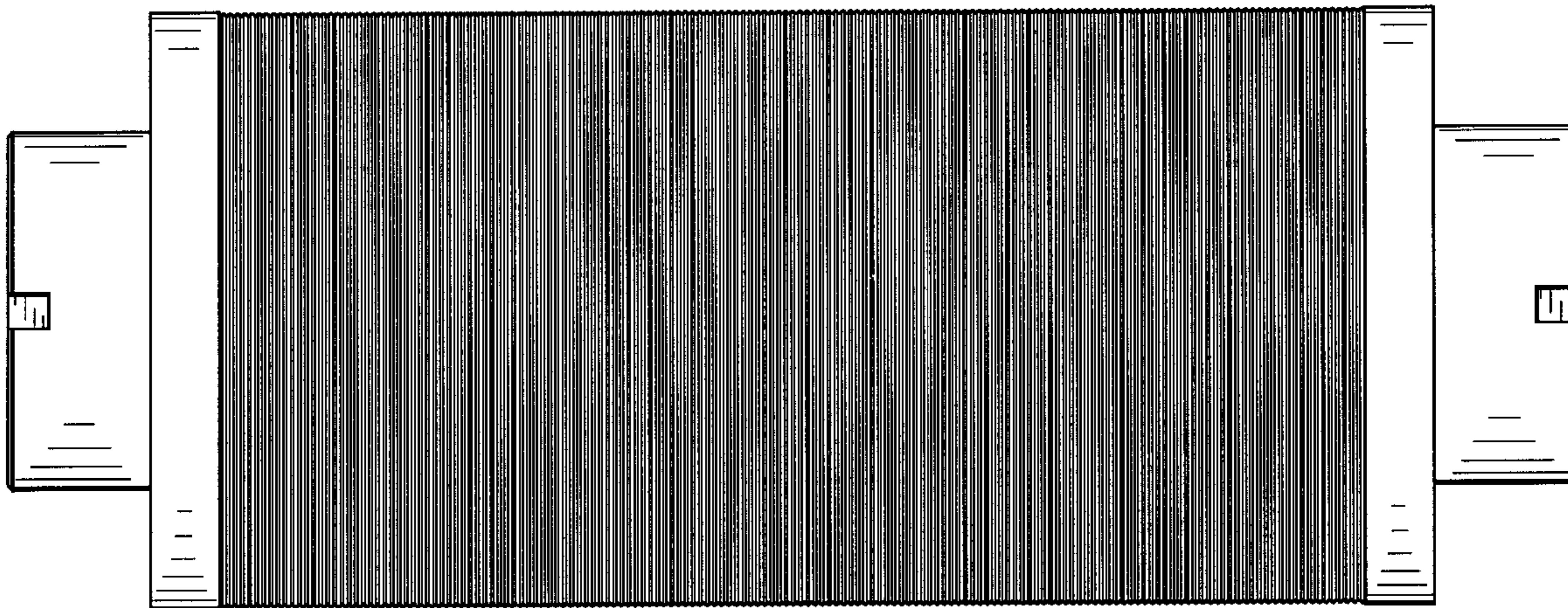
FIG. 5 is a referential view showing location of the present article in a wire saw for semiconductors.

[56] **References Cited**

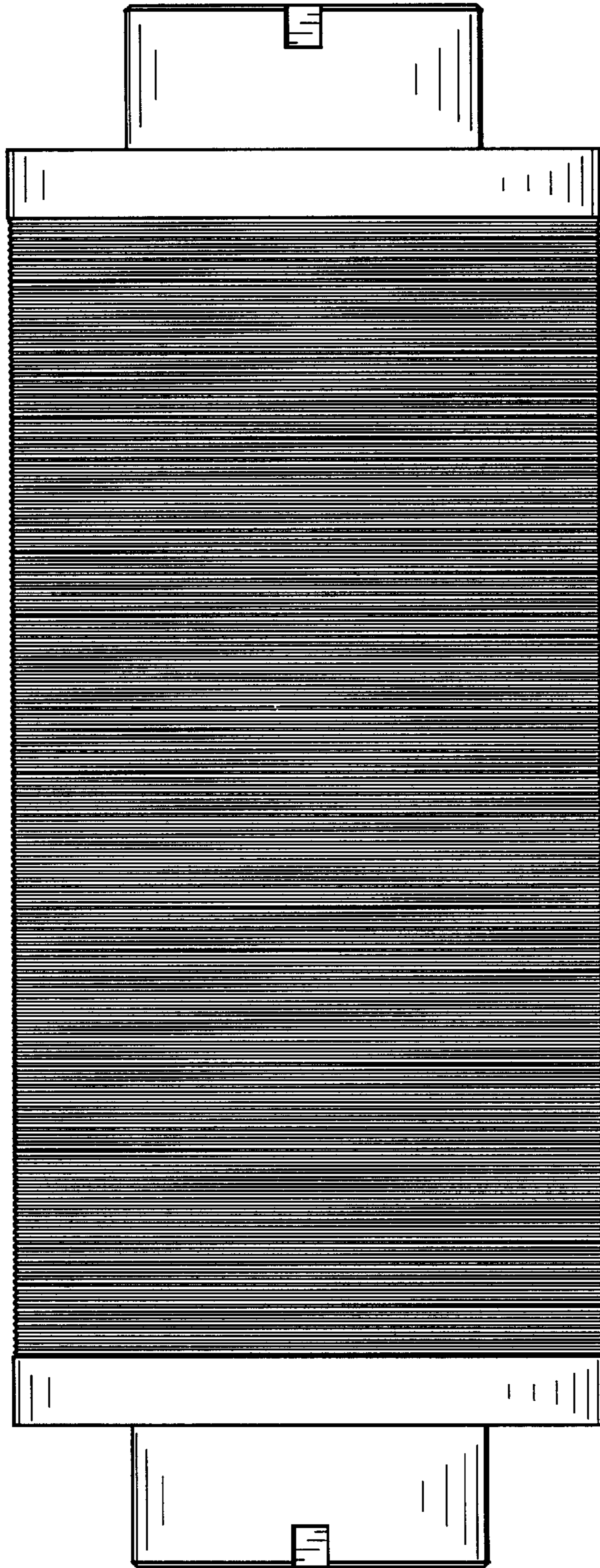
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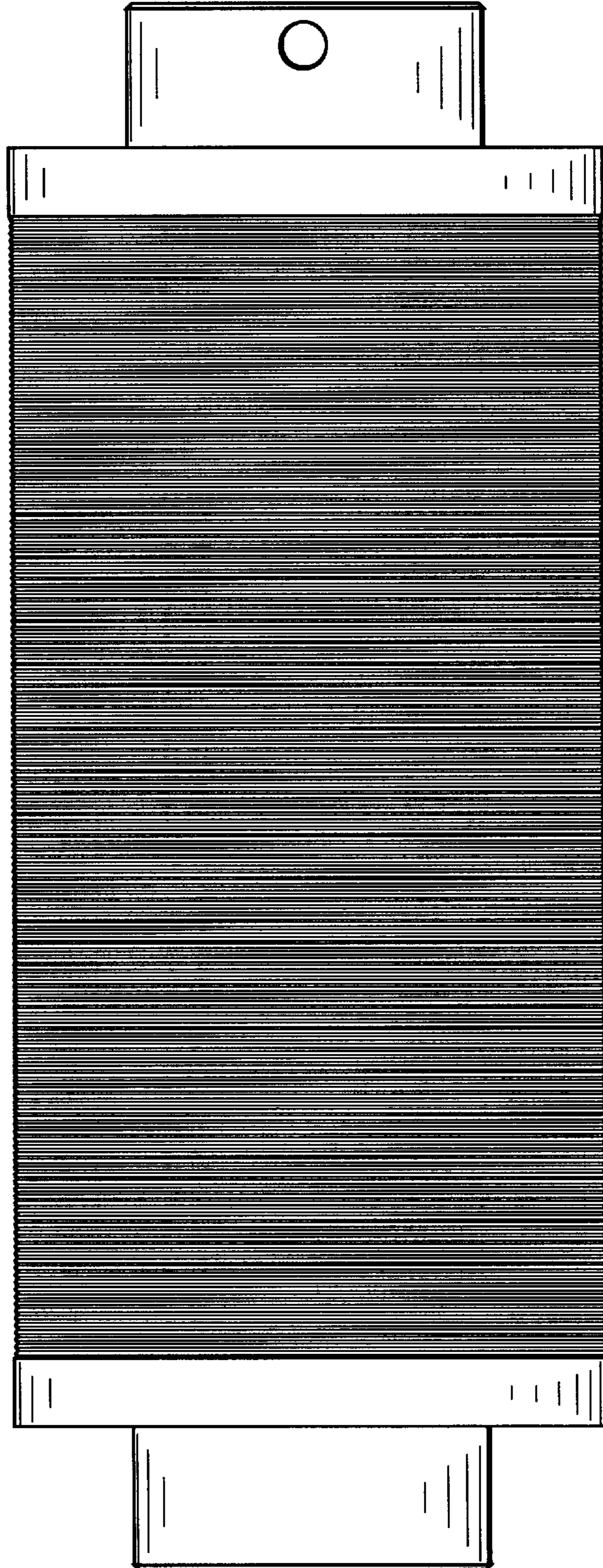
**1 Claim, 5 Drawing Sheets**



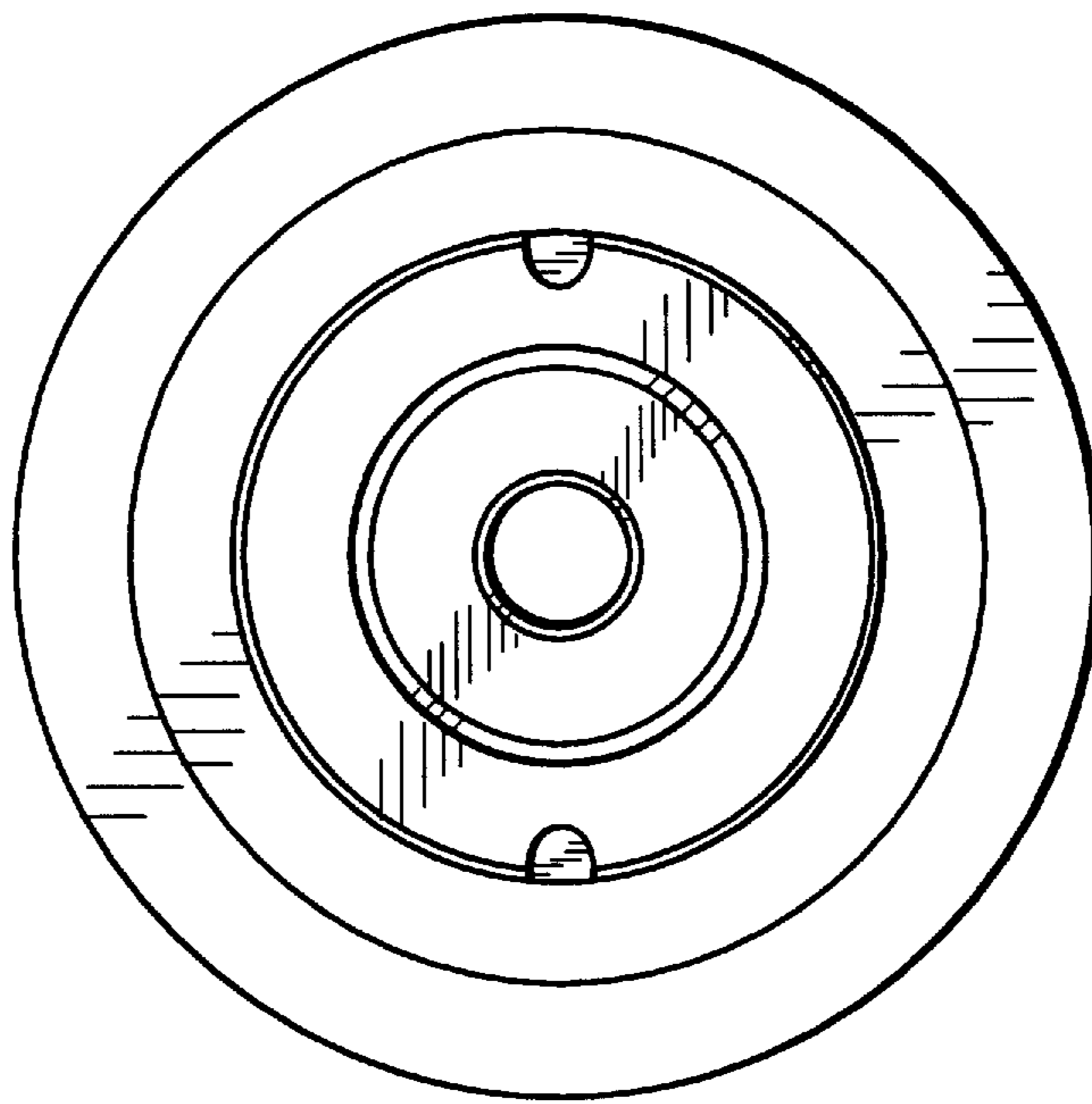
**Fig. 1**



*Fig. 2*



**Fig. 3**





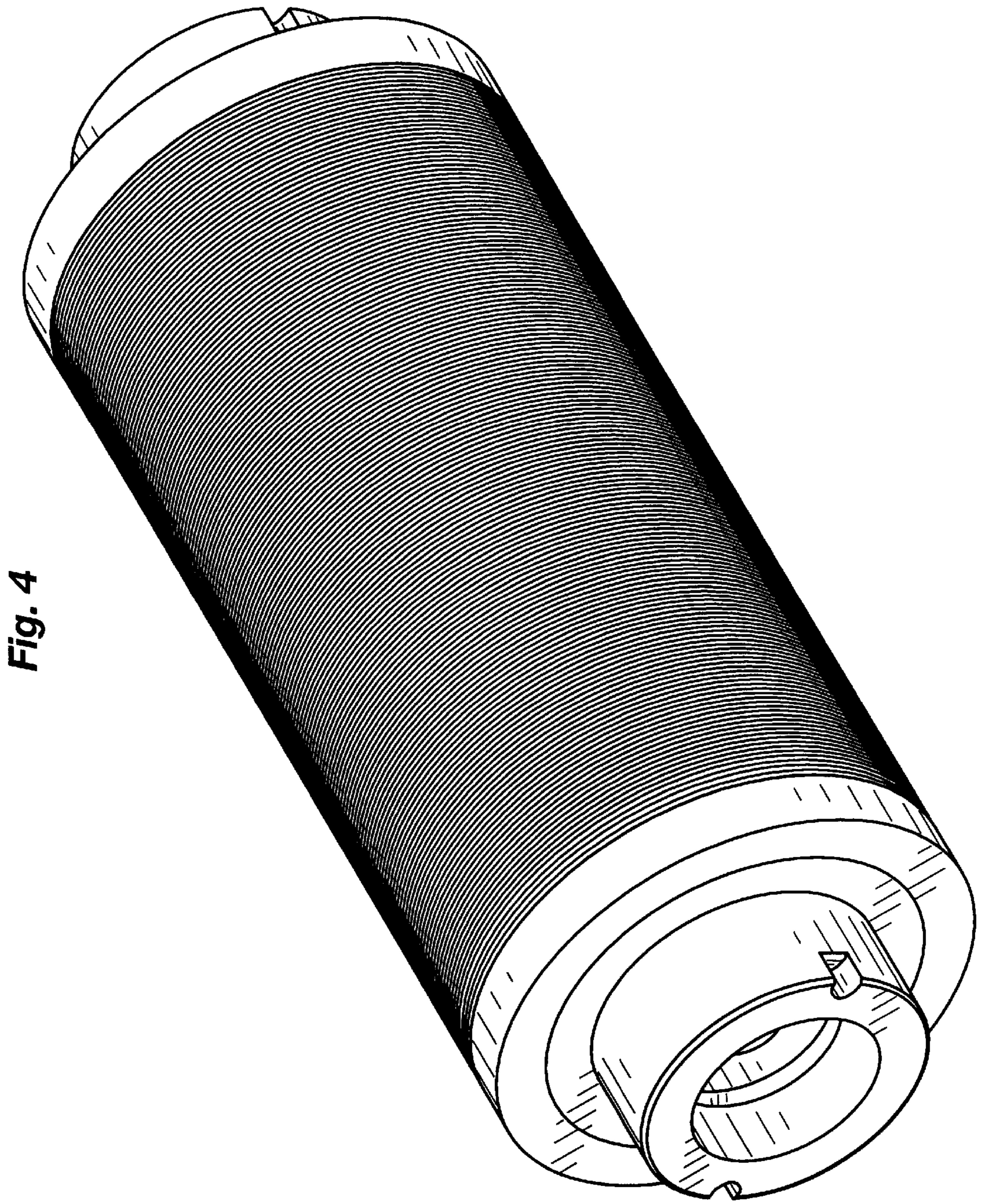


Fig. 4

Fig. 5

